Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.013”**

**ANODE**

**.007 x .007”**

**BACKSIDE IS CATHODE**

**.013”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .007” X .007”**

**Backside Potential: Cathode**

**Mask Ref: CPZ18**

**APPROVED BY: SL DIE SIZE .013” X .013” DATE: 7/26/23**

**MFG: CENTRAL SEMI THICKNESS .008” P/N: 1N4680**

**DG 10.1.2**

#### Rev B, 7/19/02